

12/30/2009

1A High-Brightness LED Driver with Integrated NMOS Switch

REV : 00

General Description

The LD7860 is a controller for step-down converters, operating in continuous conduction mode and ideally for driving high brightness of power LEDs. The device operates with inputs from 6V to 30V and utilizes an external high-side current sense resistor to set the normal average output current of up to 1A. Depending on the selection of input voltage and external components, it can drive up to 7pcs of WLEDs (VF=3.5V). Output current can be adjusted below the set value, by applying an external analog or PWM control signal to DIM pin. The device can operate with the switching frequency of up to 1MHz, making it ideal for the applications requiring small footprint and low value external inductors. Some additional features include under-voltage lockout, over current protection and thermal shutdown.

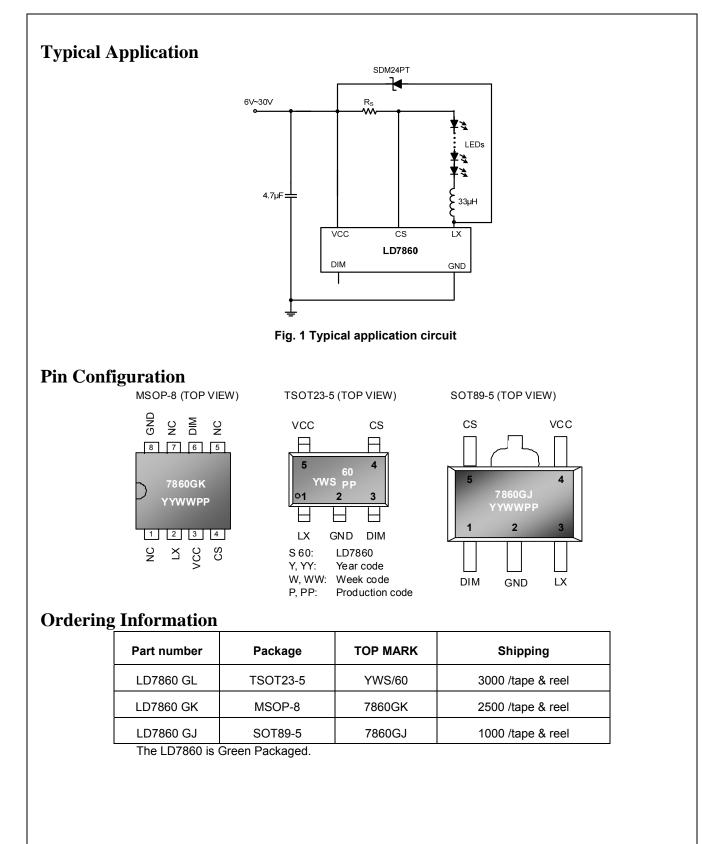
Features

- Wide input voltage range: 6V to 30V
- Integrated with 30V NMOS switch
- Up to 1A output current
- Hysteretic Control
- Output current accuracy for ±5% (typ.)
- Up to 1MHz switching frequency
- Brightness control using analog or PWM signal
- High efficiency
- Over current protection
- Over temperature protection
- Inherent open-circuit LED protection
- Output shutdown

Applications

- MR16 or LED bulbs
- Architectural, Ambient and Low-voltage industrial lightings
- LED replacement for Low-voltage halogen
- General lighting applications
- Indicators or emergency lighting
- LED back-up lighting







Pin Descriptions:

MSOP-8

PIN	NAME	FUNCTION			
1	NC	No connection.			
2	LX	Drain of NMOS switch			
3	VCC	Input voltage (from 6V to 30V). Bypass this pin with a 4.7μ F of ceramic capacitor or larger one to GND.			
4	CS	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$			
5	NC	No connection.			
6	DIM	 Remain floating during normal operation. (V_{DIM}=5V) Dimming can be accomplished by analog or by PWM control, depending on the desired applications. If V_{DIM} is below 0.35V, IC will be disabled. Connect a capacitor from it to GND to set the soft-start time. 			
7	NC	Connect a current sense resistor between it and VCC pin to set average LED current $I_{LEDAVG}(A)=0.1(V)/R_{S}(\Omega)$ with DIM pin floating.			
8	GND	IC GND.			

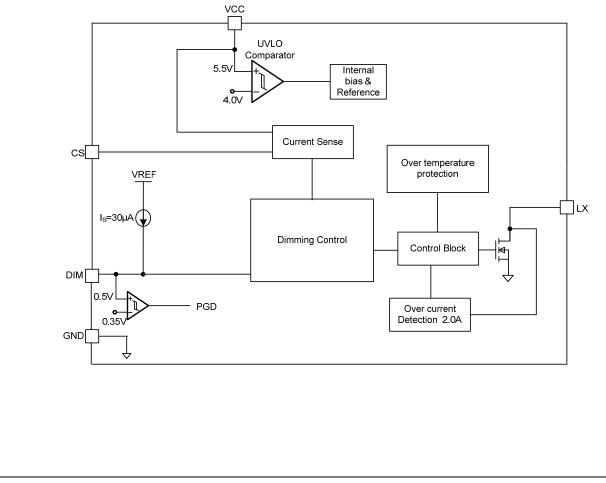
TSOT23-5

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4	Connect a current sense resistor between it and VCC pin to set average LED current $I_{LEDAVG}(A)=0.1(V)/R_{S}(\Omega)$ with DIM pin floating.				
5	VCC Input voltage (from 6V to 30V). Bypass this pin with a 4.7μ F of ceramic capacitor or larger one to GND.				



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5	CS	Connect a current sense resistor between it and VCC pin to set average LED current $I_{LEDAVG}(A)=0.1(V)/R_S(\Omega)$ with DIM pin floating.	

Block Diagram





Absolute Maximum Ratings

VCC and CS Pin to GND	-0.3V~32V (33V for 0.5s)
LX Pin to GND	-0.3V~33V (34V for 0.5s)
LX Current	3.5A
DIM Pin to GND	-0.3V~6V
Power dissipation TSOT-25@Ta=25°C	454mW
Package Thermal Resistance TSOT-25	220°C/W
Power dissipation SOT89-5@Ta=25°C	571mW
Package Thermal Resistance SOT89-5	175°C/W
Power dissipation MSOP-8@Ta=25 [°] C	625mW
Package Thermal Resistance MSOP-8	160°C/W
Operating Ambient Temperature Range	-30°C to 85°C
Storage Temperature Range	-55°C to 125°C
Maximum Operating Junction Temperature	125 [°] C
Lead Temperature (Soldering, 10sec)	260 °C
ESD Level (Human Body Model)	2kV
ESD Level (Machine Model)	200V

Caution:

Stresses beyond the ratings specified in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied





Electrical Characteristics

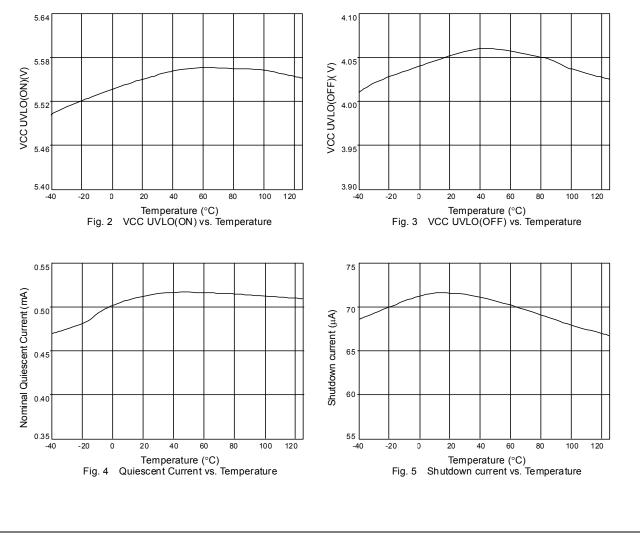
 $(T_A = +25^{\circ}C, VCC=12V \text{ unless otherwise stated})$

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Input Power					
Operating Voltage VCC		6		30	V
UVLO(ON)		5.25	5.5	5.75	V
UVLO(OFF)		3.75	4.0	4.25	V
VCC de-bounce time			5		μS
Nominal Quiescent Current, I _Q	DIM= floating		0.8	1.5	mA
Shutdown Current, I _{SD}	DIM= GND		60	100	μA
Sense Comparator					
V _{SENSE}	Mean Value of Sense Voltage DIM= floating	95	100	105	mV
V _{SNHYS}	Hysteresis voltage of VSENSE		±15		mV
Comparator from H to L Propagation Delay Time, T _{DH} .	Rising edge of V_{SENSE} delay to LX low.		80		ns
Comparator from L to H Propagation Delay Time, T _{DL} .	Falling edge of V_{SENSE} delay to LX high.		80		ns
Current Sense Input Current, I _{SENSE}	V _{SENSE} = (VCC-V _{CS})=100mV			10	μΑ
DIM					
Internal Current Source, I _S	Measurement on DIM pin R _{ADJ} =20kΩ~83.3kΩ		30		μA
V _{DIM}	V _{DIM} voltage range for analog dimming control	0.5		2.5	V
V _{DIM} de-bounce time			2		μS
V _{DIM} On/Off Threshold	Enabled Disabled	0.5		0.35	V V
Duration Low Status of Off-Time to Shutdown	V _{DIM} =Low	10			ms



PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS	
LX						
LX Leakage Current, I _{LX(leakage)}	V _{LX} =30V			5	μA	
R _{DS(ON)}	Switch on resistance, I _{LX} =1A		0.4	0.6	Ω	
Over Current Protection			2.0		А	
Others						
TSD	Thermal shutdown threshold		150		°C	
THYS	Thermal shutdown threshold hysteresis		30		°C	
Recommended switching frequency range, fS		20		1000	kHz	

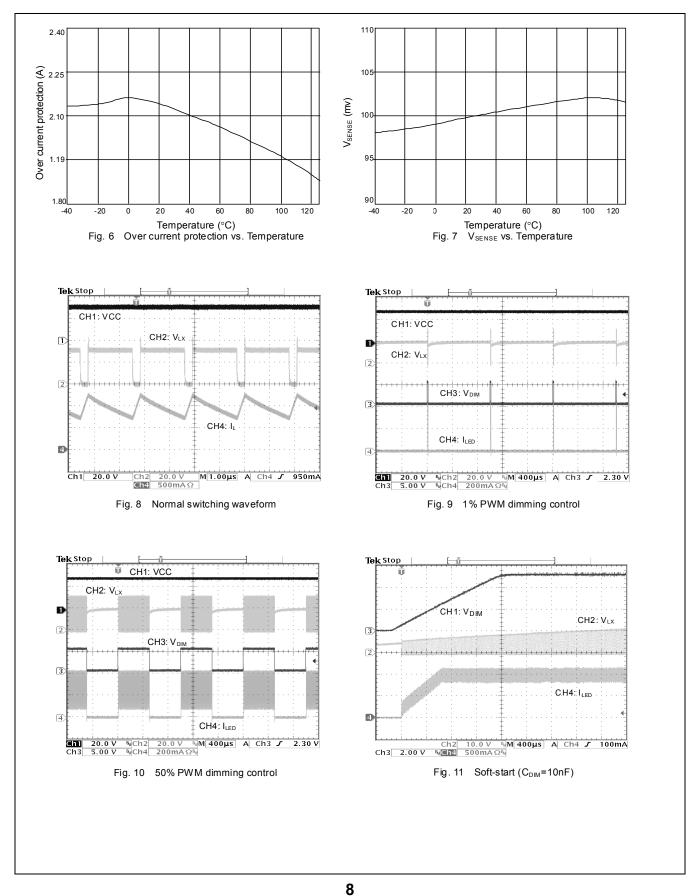
Typical Performance Characteristics



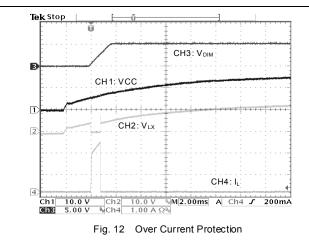
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Function Description

LED Current Program

The normal average LED current can be set through an external high-side current sense resistor, R_{S_i} which is connected between VCC pin and CS pin. The following equation can be used to calculate the current sense resistor, R_S

 $R_{S}(\Omega) = 0.5 \frac{\left(V_{SENSE(H)} + V_{SENSE(L)}\right)(V)}{I_{LEDave}(A)}$

The table below lists various average LED current and the associated current sense resistor, R_{S} .

Average LED ourrept (A)	P. (0)
Average LED current (A)	R _S (Ω)
1.0	0.1
0.7	0.143
0.35	0.286
0.3	0.333

In order to obtain accurate LED average current, high precision of current sense resistors are preferred (1% is strongly recommended).

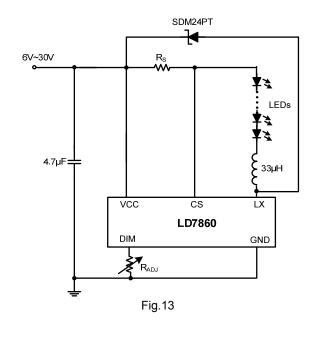
Analog Dimming Control

The analog dimming can be achieved by putting an

adjustable R_{ADJ} between DIM pin and GND to adjust the averaged LED current. Floating or pulling DIM pin high above 2.5V will achieve the maximum brightness.

The average output current in this case is given by:

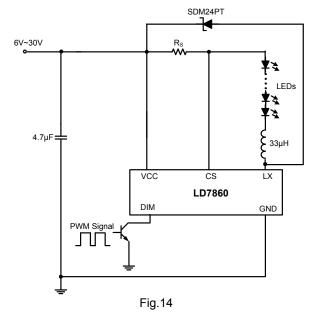
$$\begin{split} I_{LEDave} &= \frac{V_{DIM}}{2.5V} \cdot \frac{0.1V}{R_S} \text{ (A)} \\ V_{DIM} &= 30 \,\mu\text{A} \cdot \text{R}_{ADJ} \text{ (V)} \quad (20 \text{k}\Omega \leq \text{R}_{ADJ} \leq 83.3 \text{k}\Omega) \end{split}$$





PWM Dimming Control

The PWM dimming control can be achieved by applying DIM pin external PWM signal with a logic high level of above 2.5V and a minimum pulse width of 5μ s to adjust the averaged LED current by the duty cycle, which is proportional to the brightness of LED. The PWM signal can be generated by a microcontroller or a pulse generator for the duty cycle. The frequency of the PWM signal should be high enough to avoid from visibly-flashing of LED. The frequency of the PWM signal for DIM pin is recommended to be in the range from 200Hz to 1kHz.



Shutdown Mode

The LD7860 will enter shutdown mode soon as DIM pin provides voltage of logic low signal for over 10ms. During shutdown, the suspend current for the device will be less than 100μ A (max).

Soft Start

The soft start can be activated through an external soft start capacitor C_{DIM} between DIM and GND (refer to Fig. 15). The soft start time can be estimated by following formula.

$T_{SS} \cong \frac{2.05 \times C_{DIM}}{I_{S}} (mS)$	
Where,	
T _{SS} : soft start time (ms)	

C_{DIM}: external soft start capacitor (nF)

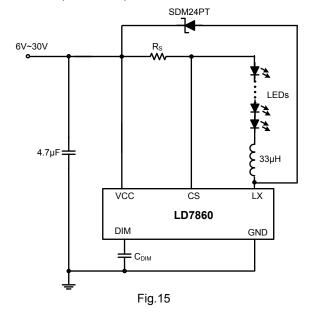
I_s: internal current source (μ A) = 30 μ A (typ.)

Example:

Assume CDIM=4.7nF

The soft start time, T_{SS} ≈2.05×4.7÷30=0.321 (ms)

If the soft start function is not required, open this capacitor to achieve quick start-up.



Over Current protection (OCP)

OCP will be triggered if the current through LX exceeds 2.0A. Once the over-current condition is detected, the IC will be latched off and stop switching.

Inherent LED Open Circuit Protection

The LD7860 employs buck converter topology to protect the IC when there's open-circuit occurring among the LED strings. In addition, the device is free from damage since the inductor is isolated from the LX pin.

Inductor Selection

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The minimum current rating of inductor must be equal to



or over 1.5 times of the programmed average LED current. It's recommended to select inductors in the range from 12μ H to 150μ H. Larger inductor possesses less current ripple and minimizes the error due to propagations delays due to higher input voltage, lower V_{LED} and light load situation. Those inductors with lower equivalent series resistance can improve the efficiency further.

When selecting the inductor, make sure it is capable to handle the peak current without saturation even at maximum operating temperature.

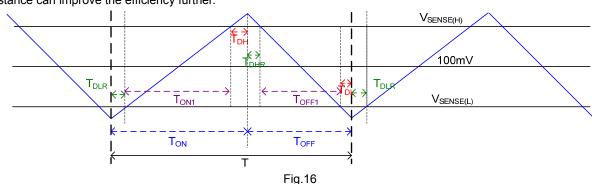


Fig. 16 illustrates the actual operating frequency of LD7860. Following it is an approximate formula.

$$f_{SW} = \frac{1}{T_{ON} + T_{OFF}} (Hz)$$

Where:

$$\begin{split} T_{ON} &= T_{ON1} + T_{DH} + T_{DLR} \rightarrow NMOS \text{ switch 'on time'(s)}. \\ T_{OFF} &= T_{OFF1} + T_{DL} + T_{DHR} \rightarrow NMOS \text{ switch 'off time'(s)}. \end{split}$$

 T_{ON} is NMOS switch on time (Neglect T_{DH} and $T_{DLR}).$ $T_{ON1} = \frac{L \cdot \Delta I}{V_{L1}}$

 T_{OFF1} is NMOS switch off time (Neglect T_{DL} and $T_{DHR}).$ $T_{OFF1} = \frac{L \cdot \Delta I}{V_{L2}}$

 V_{L1} is the across voltage of inductor when NMOS is switched on.

 $V_{L1} = VCC - V_{SENSE} - N \cdot V_{LED} - I_{LEDave} (r_{L} + R_{DS(ON)})$

 V_{L2} is the across voltage of inductor when NMOS is switched off.

$$V_{L2} = N \cdot V_{LED} + V_{FD} + V_{SENSE} + I_{LEDave} \cdot r_{L}$$

 T_{DHR} is the recovery time caused by T_{DH} .

$$T_{DHR} = \frac{V_{L1}}{V_{L2}} \cdot T_{DH}$$

 T_{DLR} is the recovery time caused by T_{DL}

$$T_{DLR} = \frac{V_{L2}}{V_{L1}} \cdot T_{DI}$$

VCC is the supply voltage (V).

L is the inductance of inductor (H).

 ΔI is the inductor peak to peak current ripple of hysteresis (A).

{Internally set for 30% of ILED(AVE)}

V_{LED} is the total forward conduction voltage of LED (V).

N is the number of LEDs.

I_{LED(AVE)} is the average LED current (A).

 r_L is the equivalent series resistance of inductor (Ω).

 $R_{DS(ON)}$ is the internal switch resistance (Ω).

 V_{FD} is the forward conduction voltage of schottky diode (V).

 T_{DH} is comparator for propagation delay time from H to L (ns).

 T_{DL} is comparator for propagation delay time from L to H (ns).



Example:

VCC=12V, V_{SENSE}=100mV, R_S=0.286 Ω , L=33 μ H, r_L=0.124 Ω , V_{LED}=3.5V, V_{FD}=0.36V, number of LED =1, I_{LED(AVE)}=350mA. Actual operating frequency: f_S = $\frac{1}{T_{ON} + T_{OFF}}$ = 605.46 kHz

The operating frequency between 20 kHz and 1MHz will effectively suppress the audible noise.

Diode Selection

With lower forward voltage and quick reverse recovery, the fast schottky diode offers improved efficiency and performance. To prevent any breakdown or leakage, its peak current rating of the diode is required for higher than the current through the inductor, the continuous current rating higher than the RMS value of LED current, and also, the voltage rating higher than the peak input voltage transient.

Recommended T_{ON} and T_{OFF}

Set T_{ONMIN} and T_{OFFMIN} for more than 300ns and 350ns respectively in order to enhance output current precision against propagation delay time.

Input Capacitor Selection

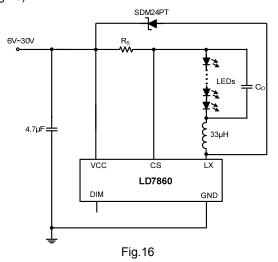
Since ceramic capacitors features high ripple rating, low ESR, low cost, and tiny size, it's an ideal companion part for LD7860. Place a capacitor of at least 4.7μ F between VCC and GND to ensure steady input voltage and filter out the pulsing input current. The minimum distance between the IC and capacitor is, the maximum efficiency will achieve. To obtain constant capacitance over temperature and voltage, capacitors with X5R, X7R or better dielectric are recommended.

Output Capacitor

In most cases, the LED current ripple is equal to the

LD7860

inductor current ripple. If it's required to minimize LED's current ripple, just place an output capacitor across the LED's terminals. An output capacitor C_0 connected in parallel with the LEDs can reduce the LED's current ripple while there's same average current flowing through both the inductor and the LEDs. See below for the application. (Fig.16)



Just a 1μ F output capacitor is required to reduce the LED current ripple remarkably. Its capacitance will not affect the switching frequency, overall efficiency and the average LED current value.

The following approximate equation will give calculation for LED's current ripple, Δi_R .

$$\Delta i_{R} = \Delta i_{L} \cdot \frac{Z_{c}}{Z_{c} + r_{d}}$$

Where

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 $\Delta \, i_L$ is the inductor current ripple

Z_C is the equivalent impedance of output capacitor

r_D is the LED dynamic resistance

The calculation for Z_C assumes the shape of the inductor current is approximately sinusoidal.

Thermal consideration

Most LED drivers usually operate in high ambient temperature, so IC junction is a crucial issue in the applications. It's recommended to control the junction



temperature under 125°C. $P_{D(MAX)} = \frac{(125°C - T_A)}{\theta_{JA}}$

 $P_{D(MAX)}$ = the power consumption for the IC θ_{JA} : Package Thermal Resistance

Layout Consideration

- Place the VCC bypass capacitor, $4.7\mu F$ at least, much near VCC pin and GND pin.
- Place the flywheel diode and inductor near the LX pin.
- · Locate the current sense resistor near their

associated pins as possible. And route away from switching nodes, such as LX pin.

- The high current path should be wide and short as possible.
- CS sense path should be thin as possible and be isolated with the other pins by ground to minimize the noise and interference.
- For the sake of noise depression, a 33pF ceramic capacitor is recommended to place between CS and GND.

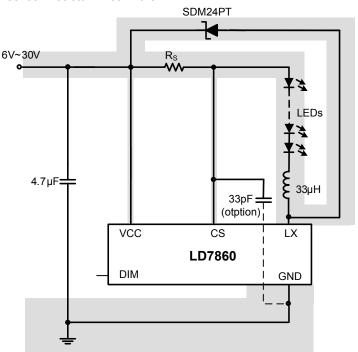
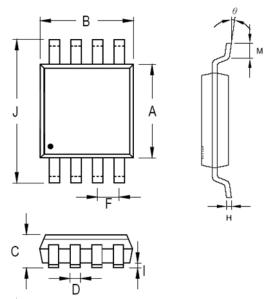


Fig. 17 the recommended PCB layout



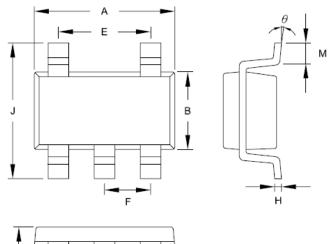
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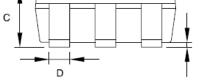


Querrahal	Dimension in Millimeters		Dimensions in Inches	
Symbol	Min	Max	Min	Max
А	2.896	3.099	0.114	0.122
В	2.896	3.099	0.114	0.122
С	0.813	1.219	0.032	0.048
D	0.220	0.380	0.009	0.015
F	0.65 TYP.		0.026 TYP.	
Н	0.127	0.229	0.005	0.009
I	0.050	0.150	0.002	0.006
J	4.699	5.105	0.185	0.201
М	0.400	0.800	0.016	0.031
θ	0 [°]	6 [°]	0°	6°



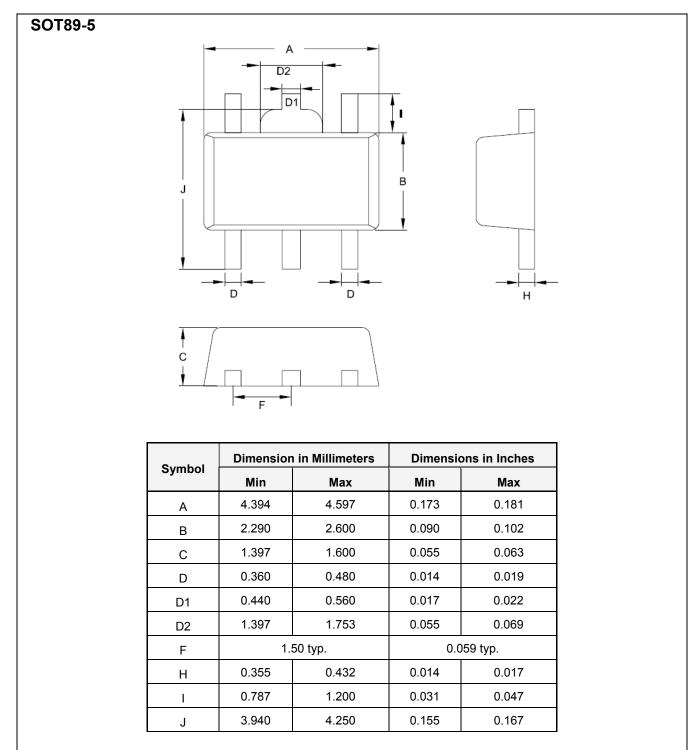
TSOT23-5





Symbol	Dimension in Millimeters		Dimensions in Inches		
Symbol	Min	Мах	Min	Max	
А	2.692	3.099	0.106	0.122	
В	1.397	1.803	0.055	0.071	
С	0.750	0.900	0.030	0.035	
D	0.300	0.500	0.012	0.020	
E	1.90 TYP		0.074 TYP		
F	0.95 TYP		0.037 TYP		
н	0.080	0.254	0.003	0.010	
I	0.000	0.150	0.000	0.006	
J	2.600	3.000	0.102	0.118	
М	0.300	0.600	0.012	0.024	
θ	0°	10°	0°	10°	





Important Notice

Leadtrend Technology Corp. reserves the right to make changes or corrections to its products at any time without notice. Customers should verify the datasheets are current and complete before placing order.



Revision History

Rev.	Date	Change Notice
00	12/30/2009	Original Specification